



## 3D Packaging & Integration North America TC Chapter

SEMI Standards NA Fall Meetings 2026

Tuesday, September 22

Online via Official Virtual Technical Committee Chapter Meeting (OVTCCM)

08:00–09:30 Pacific

### AGENDA

|                                                                                                                                                | Time         |
|------------------------------------------------------------------------------------------------------------------------------------------------|--------------|
| <b>1 Welcome/Call to Order</b>                                                                                                                 | <b>08:00</b> |
| 1.1 Please log into <a href="https://web.portal.semi.org/meetings">https://web.portal.semi.org/meetings</a> for voting                         |              |
| 1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)               |              |
| 1.3 Introductions                                                                                                                              |              |
| 1.4 Agenda Review                                                                                                                              |              |
| <b>2 Liaison Reports</b>                                                                                                                       | <b>08:15</b> |
| 2.1 Japan TC Chapter                                                                                                                           |              |
| 2.2 Taiwan TC Chapter                                                                                                                          |              |
| <b>3 Staff Report</b>                                                                                                                          | <b>08:25</b> |
| <b>4 Review of Previous Meeting Minutes (<i>from Winter Meetings 2026</i>)</b>                                                                 | <b>08:30</b> |
| <b>5 Ballot Review</b>                                                                                                                         | <b>08:35</b> |
| 5.1 Document 7369 — Line-Item Revision to SEMI 3D20-0921, Specification for Panel Characteristics for Panel Level Packaging (PLP) Applications |              |
| <b>6 Task Force Updates</b>                                                                                                                    | <b>09:00</b> |
| 6.1 3DP&I Bonded Wafer Stacks and Inspection & Metrology Task Forces                                                                           |              |
| 6.2 Panel Level Packaging (PLP) Panel Task Force                                                                                               |              |



|                                                                                                                                                                                                                                                                                                                                                   | Time         |
|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|
| <b>7 Old Business</b>                                                                                                                                                                                                                                                                                                                             | <b>09:10</b> |
| 7.1 Five-Year Review                                                                                                                                                                                                                                                                                                                              |              |
| • SEMI 3D8-1121: Guide for Describing Silicon Wafers for Use as 300 mm Carrier Wafers in a 3DS-IC Temporary Bond-Debond (TBDB) Process                                                                                                                                                                                                            |              |
| • SEMI 3D13-0715 (Reapproved 0222): Guide for Measuring Voids in Bonded Wafer Stacks                                                                                                                                                                                                                                                              |              |
| • SEMI 3D2-0216 (Reapproved 0222): Specification for Glass Carrier Wafers for 3DS-IC Applications                                                                                                                                                                                                                                                 |              |
| <b>8 New Business</b>                                                                                                                                                                                                                                                                                                                             | <b>09:15</b> |
| <b>9 Action Item Review</b>                                                                                                                                                                                                                                                                                                                       | <b>09:20</b> |
| <b>10 Next Meeting and Adjournment</b>                                                                                                                                                                                                                                                                                                            | <b>09:25</b> |
| 10.1 The next SEMI Standards NA Meetings are tentatively scheduled for the week of March 30-April 1, 2027, to be held in-person and virtually in conjunction with SEMICON West in Phoenix, Arizona. Schedule details TBD. <a href="https://www.semi.org/en/products-services/standards">https://www.semi.org/en/products-services/standards</a> . |              |
| <b>Tentative Schedule:</b>                                                                                                                                                                                                                                                                                                                        |              |
| Thursday, April 1 (Mountain)                                                                                                                                                                                                                                                                                                                      |              |
| ○ Joint TFs meeting 11:00-12:00 Noon                                                                                                                                                                                                                                                                                                              |              |
| ○ TC Chapter 13:00-14:30                                                                                                                                                                                                                                                                                                                          |              |

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